

WHAT IS CLAIMED IS:

1. An organic film vapor deposition method comprising:

a first step of supporting a substrate formed with a scintillator on at least three protrusions of a target-support element disposed on a vapor deposition table so as to keep a distance from said vapor deposition table;

a second step of introducing said vapor deposition table having said substrate supported by said target-support element into a vapor deposition chamber of a CVD apparatus; and

a third step of depositing an organic film by CVD method onto all surfaces of said substrate, provided with said scintillator, introduced into said vapor deposition chamber in a state that said substrate is supported so as to keep a distance from said vapor deposition table.

2. An organic film vapor deposition method according to claim 1, wherein said target-support element is constituted by at least three target-support needles.

3. An organic film vapor deposition method according to claim 1, wherein said target-support element is constituted by a strand member.

4. An organic film vapor deposition method according to claim 1, wherein said organic film is a polyparaxylylene film.

## 5. A scintillator panel with organic film

deposited by the method according to claim 1.

6. A scintillator panel comprising:

a substrate;

a scintillator formed on said substrate; and

5 an organic film covered substantial all surfaces of  
said substrate not only over the scintillator side but also  
over the opposite side.

7. A scintillator panel according to claim 6,  
wherein said organic film is a polyparaxylylene film.

10

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